

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

1. (Currently amended) A connector assembly for providing a radio frequency (RF) signal path to a chip carrier, said connector assembly comprising:
 - a body having an inner cylindrical portion and an outer cylindrical portion;
 - a flange connected to the body and having a cavity, wherein the cavity receives a chip carrier; ~~[[and]]~~
 - ~~an RF interconnect structure including a plurality of pins extending from the cavity; and~~
 - ~~a support member within the body, wherein the support member supports at least one of the pins inside the body flange, wherein the cavity of the flange receives a chip carrier and the pins contact the chip carrier.~~
2. (Original) The connector assembly according to claim 1, wherein the plurality of pins have a coplanar pin configuration and include at least one signal pin and a ground pin.
3. (Original) The connector assembly according to claim 2, wherein the signal pin is connected to a device in the chip carrier.
4. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein ~~[[a]]~~ the signal path between the signal pin of the connector and the device in the chip carrier is less than 500 mils.

5. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is
less than 400 mils.

6. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is
less than 300 mils.

7. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is
less than 200 mils.

8. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is
less than 100 mils.

9. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is
less than 75 mils.

10. (Currently Amended) The connector assembly according to ~~claim 1~~ claim 3, wherein
[[a]] the signal path between the signal pin of the connector and the device in the chip carrier is
less than 40 mils.

11. (Original) The connector assembly according to claim 1, wherein the cavity receives a substantial portion of the chip carrier.

12. (Original) The connector assembly according to claim 1, wherein the chip carrier is substantially flush with a surface of the flange.

13. (Original) The connector assembly according to claim 1, wherein the cavity is located at a center portion of the flange.

14. (Original) The connector assembly according to claim 13, wherein the cavity is symmetrically centered in the flange.

15. (Original) The connector assembly according to claim 1, wherein the chip carrier includes one of a semiconductor device and an optical driver.

16. (Original) The connector assembly according to claim 1, wherein the plurality of pins have a coplanar pin configuration and include a signal pin and two ground pins, the signal pin being connected to a device in the chip carrier.

17. (Original) The connector assembly according to claim 16, wherein the chip carrier includes a conductive line connecting the signal pin of the connector to the device in the chip carrier.

18. (Original) The connector assembly according to claim 17, wherein the conductive line is coplanar with the signal pin.

19. (Original) The connector assembly according to claim 18, wherein the conductive line is bent prior to contacting the device.

20. (Original) The connector assembly according to claim 17, wherein the conductive line is less than 100 mils.

21. (Original) The connector assembly according to claim 17, wherein the conductive line is less than 50 mils.